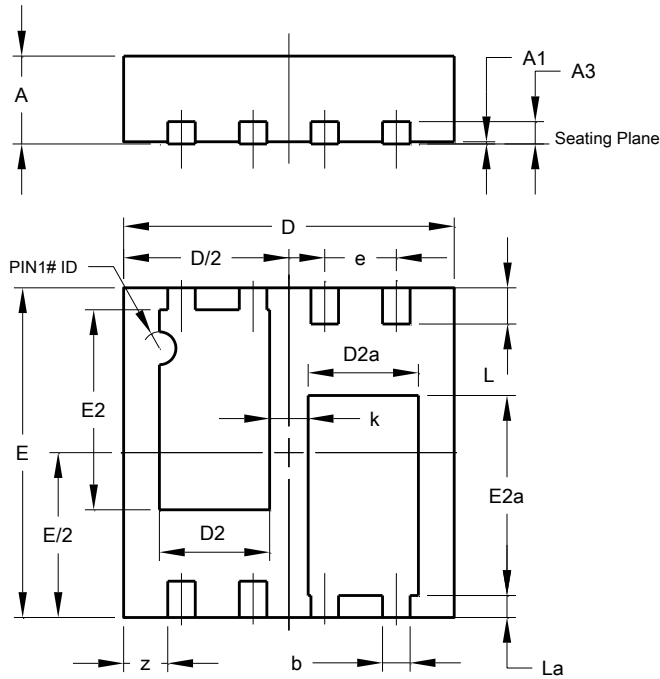


**Package Outline Dimensions**

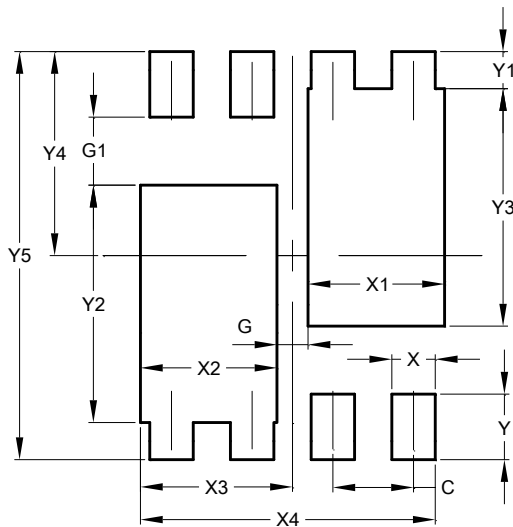
V-DFN3030-8 (Type J)



V-DFN3030-8 (Type J)			
Dim	Min	Max	Typ
A	0.77	0.83	0.80
A1	0.00	0.05	0.02
A3	0.203 BSC		
b	0.20	0.30	0.25
D	2.95	3.050	3.00
D2	0.90	1.10	1.00
D2a	0.90	1.10	1.00
E	2.95	3.050	3.00
E2	1.72	1.92	1.82
E2a	1.72	1.92	1.82
e	0.65BSC		
L	0.27	0.38	0.33
La	0.15	0.25	0.20
k	0.35 TYP		
z	0.40 BSC		
All Dimensions in mm			

**Suggested Pad Layout**

V-DFN3030-8 (Type J)



Dimensions	Value (in mm)
C	0.650
G	0.250
G1	0.550
X	0.350
X1	1.100
X2	1.100
X3	1.225
X4	2.375
Y	0.530
Y1	0.300
Y2	1.920
Y3	1.920
Y4	1.650
Y5	3.300

**ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS**

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.